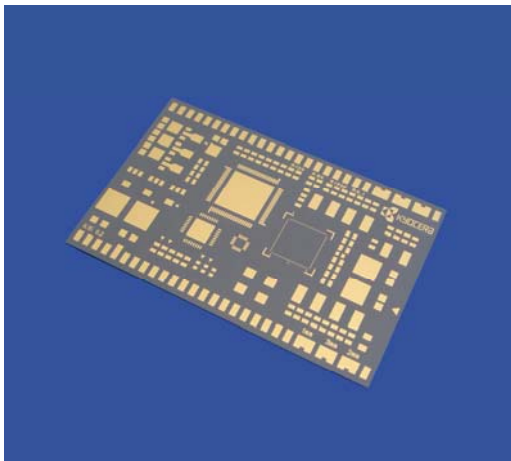


## High Power, Compact ECU Substrate

**NEW!**

Multilayer Ceramics with Low Resistance Conductor  
Enables Compact High Power ECU

### Product

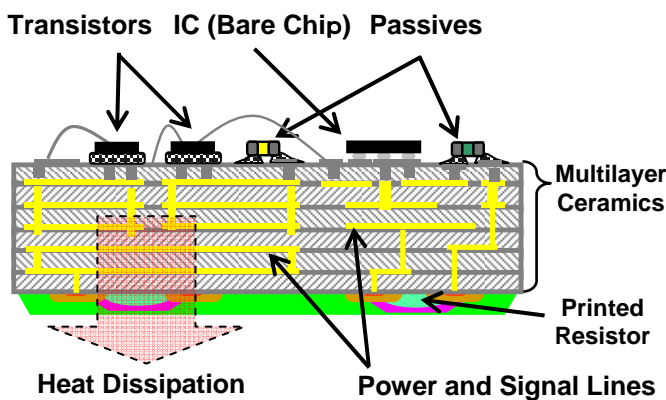


### Features

- High Current ECU Ceramic Substrate  
**Current Capacity: up to ~25A\***
- Compact Substrate by Wiring Power and Signal Lines into the Substrate
- Close CTE to Silicon Bare Chip Enables Reliable Mounting  
**CTE: 7.0ppm/K (RT ~ 400 degree C)**
- Printed Resistor Available

### Compact ECU Assembly Image

#### Cross Section



#### Thermal Conductivity

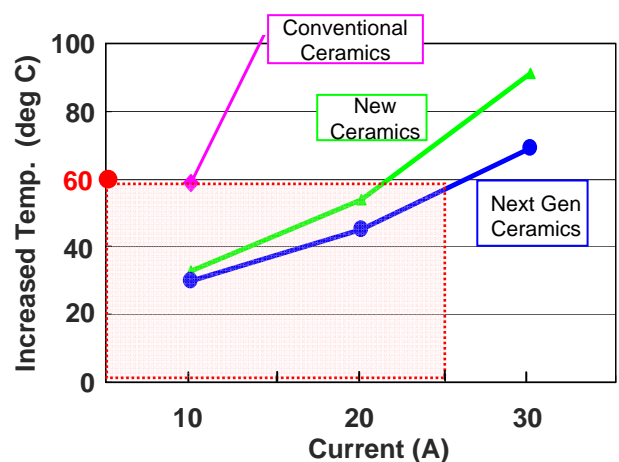
Conventional Ceramics : 18W / mk  
New / Next Gen Ceramics\* : 16W / mk

#### Sheet Resistance

Conventional Ceramics : 10mΩ / sq.  
New Ceramics : 4mΩ / sq.  
Next Gen Ceramics\* : 2mΩ / sq.

### Current Capacity

#### Current vs Ceramic Surface Temperature\*\* (Simulation Data)



\* Under Development

\*\* As for simulation method and condition please ask to Kyocera staff or website

E-mail: [webmaster.sc@kyocera.jp](mailto:webmaster.sc@kyocera.jp)

URL: <http://global.kyocera.com/sc>